



(19)

(11) Publication number:

11

Generated Document.

PATENT ABSTRACTS OF JAPAN(21) Application number: **09305885**(51) Intl. Cl.: **B24B 37/00**(22) Application date: **07.11.97**

<p>(30) Priority:</p> <p>(43) Date of application publication: 25.05.99</p> <p>(84) Designated contracting states:</p>	<p>(71) Applicant: NIKON CORP</p> <p>(72) Inventor: ISHIKAWA AKIRA</p> <p>(74) Representative:</p>
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**(54) CMP POLISHING PAD
AND POLISHING DEVICE
USING IT**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad which has the optimum hardness corresponding to the hardness of a polished object, without reducing the property of the polishing pad, and a polishing device using it.

SOLUTION: A CMP polishing pad 10 mainly contains A and B components, including bisphenol A epoxy resin, novolak epoxy resin, bisphenol F epoxy resin, or these polymer and these deformed epoxy resin, aromatic amines, aromatic acid anhydride, imidazoles, or these polymer and these deformed hardening agent, monoepoxide, polyepoxide, polythiol, polyole, polycarboxyl compound, urethane prepolymer, and flexible grafting agent of block urethane prepolymer, the surface hardness being 2.5-40 at a

epoxy

Vickers hardness.

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